

# Features

## Key features

- MLX75023 and MLX75123 ToF Chipset
- QVGA resolution
- 120 klx sunlight rejection
- VCSEL illumination (60° or 110°)
- Modulation frequency up to 40MHz
- Distance and confidence data at up to 60 fps
- Separable modules

## ToF Chipset board

- MLX75023 QVGA, 320x240 pixels, ToF sensor array IC
- MLX75123 ToF companion chip
- Standard S mount (M12x0.5) lens holder
- Temperature sensor
- Programmable input clock and VMIX voltage
- FPD-Link III serializer

## CM-I.MX6 Processor board

- Quad core i.MX6 processor running up to 1.2 GHz
- Calculates distance and confidence data
- Acts as data/control bridge
- Holds customer application (optional)

## Illumination board

- 4x VCSELs (60° or 110° field of view)
- Programmable peak optical power (0 – 25W)
- Onboard temperature sensor
- Eye safe (certificate available)

## Interface board

- Interface between ToF chipset and CM-i.MX6 Board
- FDP-Link III deserializer
- Power input (9 – 16V) and RJ45 ethernet connector
- GPIO connector (I<sup>2</sup>C, SPI, VIN, 3V3 & three GPIOs)



# Applications

- Object tracking & counting
- Machine vision systems
- Surveillance systems
- Gesture recognition
- Three dimensional mapping
- Collision detection

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## 1. Changelog

Version	Date	Changes
<b>001-005</b>	29/08/2017	Internal releases
<b>006</b>	29/08/2017	Initial public release

## 2. Ordering information

Order code	Characteristics
<b>EVK75123-60-850-1</b>	60 degrees field of view, 850nm VCSELs
<b>EVK75123-110-850-1</b>	110 degrees field of view, 850nm VCSELs

## 3. Maximum ratings

Parameter	Symbol	Values	Unit
<b>Supply voltage</b>	$V_{in}$	9 to 16 ( <b>12 typical</b> )	V
<b>Power consumption (at maximum : 600<math>\mu</math>s of Int. time, 100% illumination power, 50 fps)</b>	$P_{in\ max}$	<b>11</b>	W
<b>Power consumption (nominal parameters : 250<math>\mu</math>s of Int. time, 50% illumination power, 25 fps)</b>	$P_{in}$	7.2	W
<b>Surge current</b>	$I_{surge}$	<b>7</b>	A
<b>Current consumption (at maximum : 600<math>\mu</math>s of Int. time, 100% illumination power, 50 fps)</b>	$I_{in\ max}$	<b>0.930</b>	A
<b>Current consumption (nominal parameters : 250<math>\mu</math>s of Int. time, 50% illumination power, 25 fps)</b>	$I_{in}$	0.6	A
<b>Integration time</b>	$T_{int}$	600	$\mu$ s

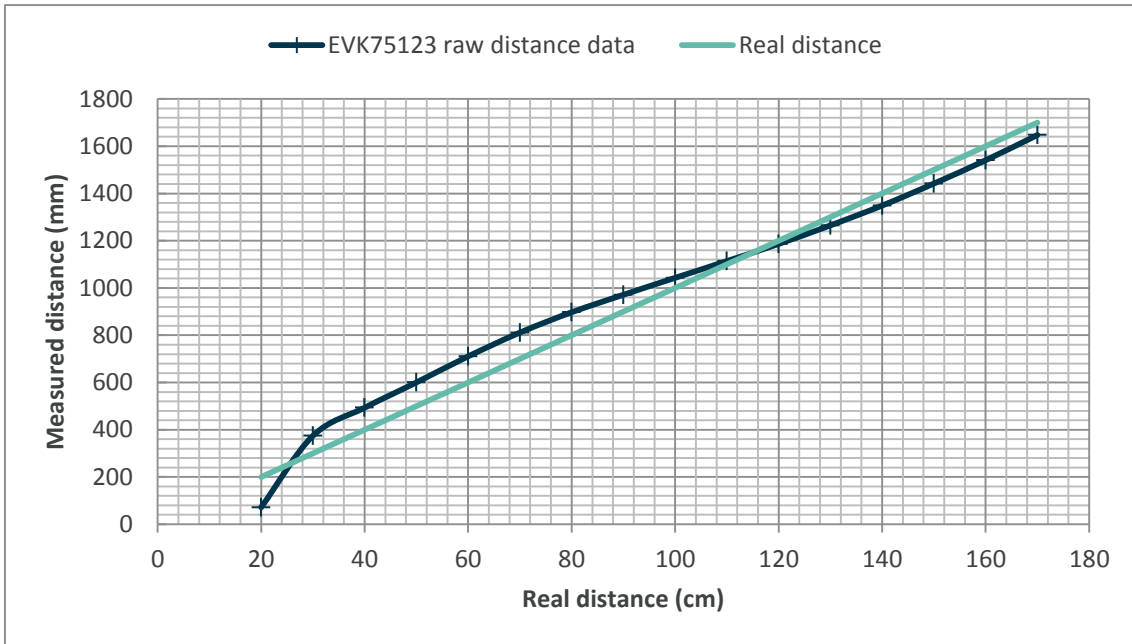
## 4. Characteristics

Parameter	Symbol	Values	Unit
<b>Modulation frequency</b>	$F_{mod}$	12 to 40 ( <b>20</b> typical)	MHz
<b>MLX75123 input clock frequency</b>	$F_{in}$	40, 48 or 80	MHz
<b>Optical power peak per steradian, in direction of optical axis, at setting 50%</b>	$P_{opt}$	19.2 (60° FoV EVK) 6.72 (110° FoV EVK)	W/sr
<b>Phase image dark noise in A-B mode</b>	$N_{Dark}$	3.6	DN

## 5. Typical performance

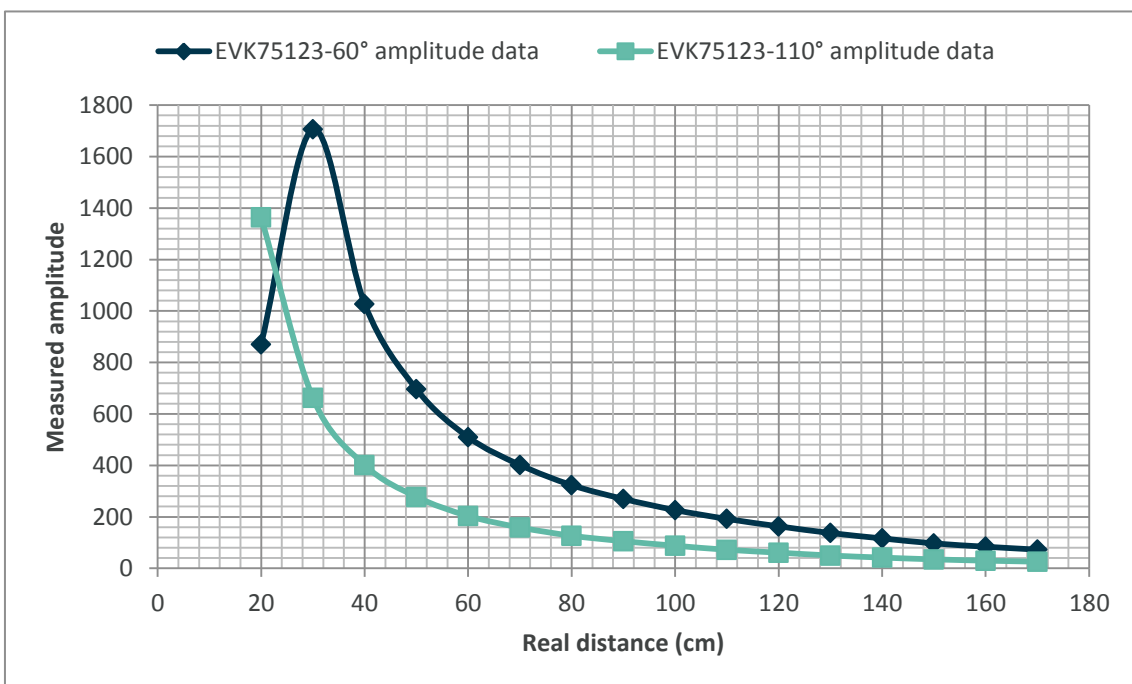
### 5.1. Linearity

Measured distance as a function of real distance,  $T_A = 25\text{ }^\circ\text{C}$ ,  $T_{int} = 250\text{ }\mu\text{s}$ ,  $F_{mod} = 20\text{ MHz}$ ,  $P_{ill} = 50\%$ , statistics over 100 frames per point.



### 5.2. Amplitude

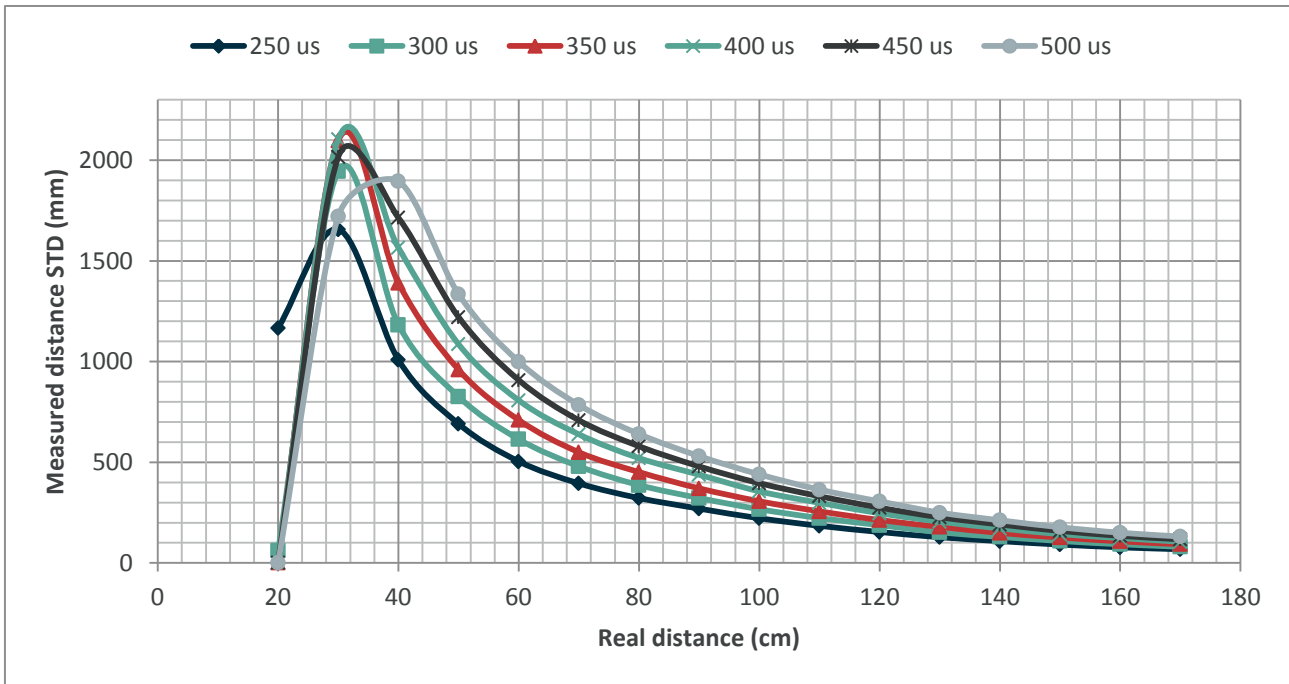
Measured amplitude as a function of real distance,  $T_A = 25\text{ }^\circ\text{C}$ ,  $T_{int} = 250\text{ }\mu\text{s}$ ,  $F_{mod} = 20\text{ MHz}$ ,  $P_{ill} = 50\%$ , statistics over 100 frames per point, target reflectance is around 50 %.



NB: Decreasing values at close range are related to the saturation of the sensor.

### 5.2.1. Influence of the integration time on the amplitude

Measured amplitude values as a function of real distance,  $T_A = 25\text{ }^\circ\text{C}$ ,  $F_{mod} = 20\text{ MHz}$ ,  $P_{ill} = 50\%$ , statistics over 100 frames per point, under office light conditions, target reflectance is around 50%. 60° FoV EVK was used.

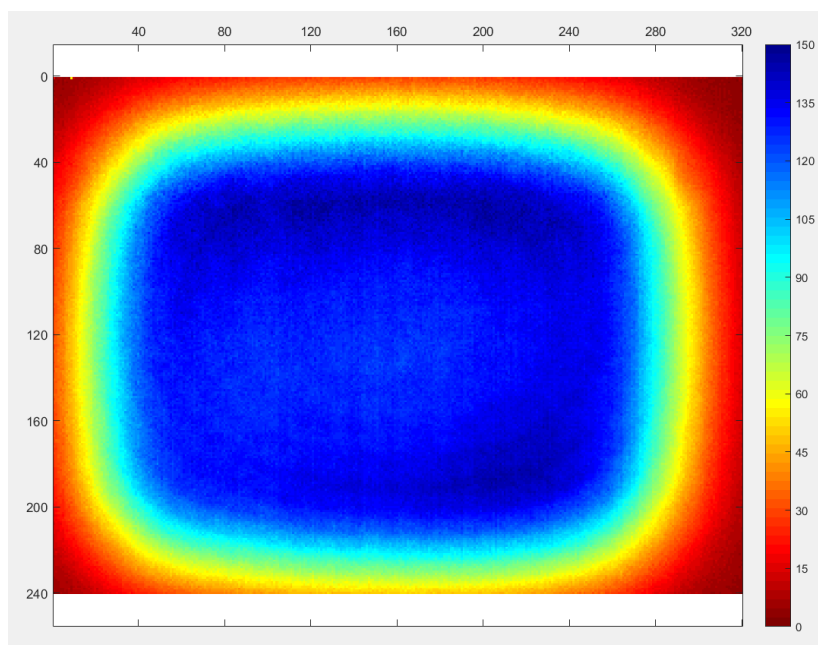


NB: Decreasing values at close range are related to the saturation of the sensor.

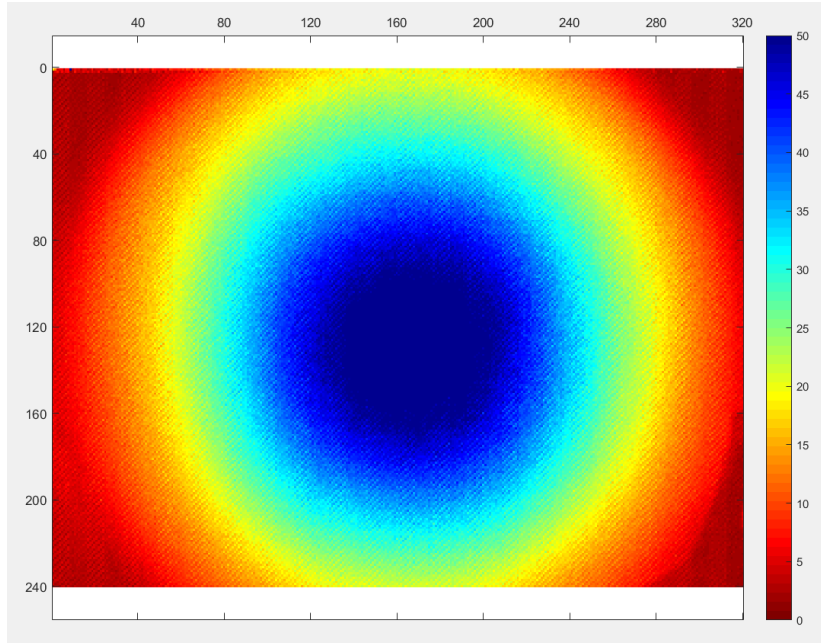
### 5.2.2. Amplitude uniformity

Measured amplitude values in front of a white wall at 1 meter,  $T_A = 25\text{ }^\circ\text{C}$ ,  $F_{mod} = 20\text{ MHz}$ ,  $P_{ill} = 50\%$ . Amplitude scale in DN indicated on the right.

#### 5.2.2.1. EVK75123 60 degrees field of view



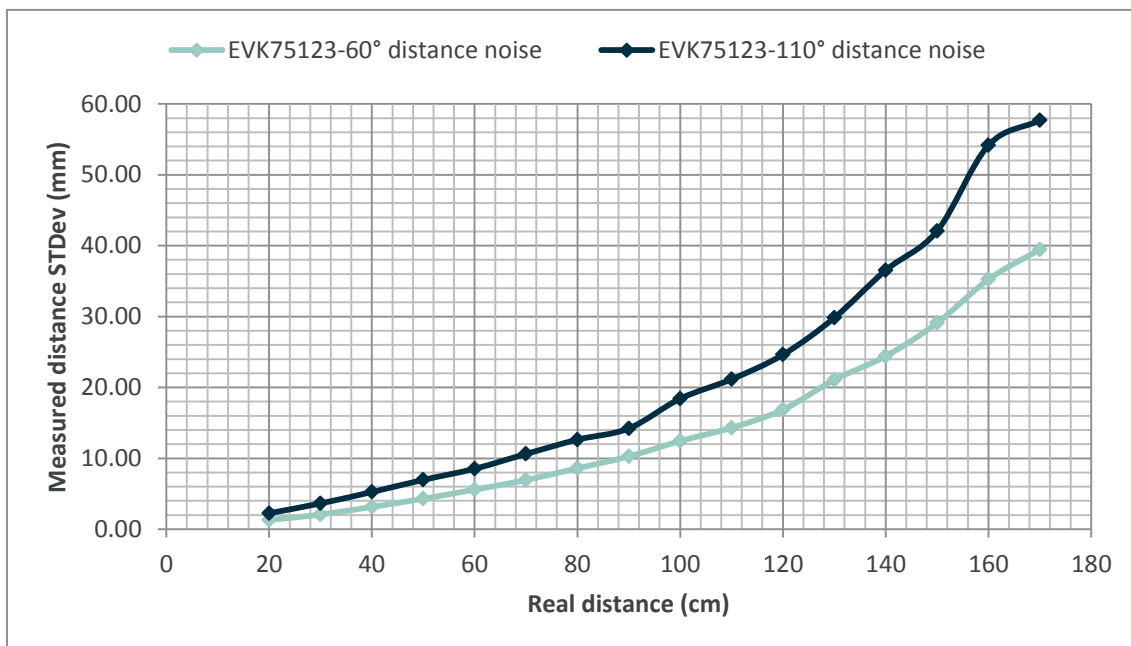
### 5.2.2.2. EVK75123 110 degrees field of view



## 5.3. Distance noise

### 5.3.1. Typical distance noise values

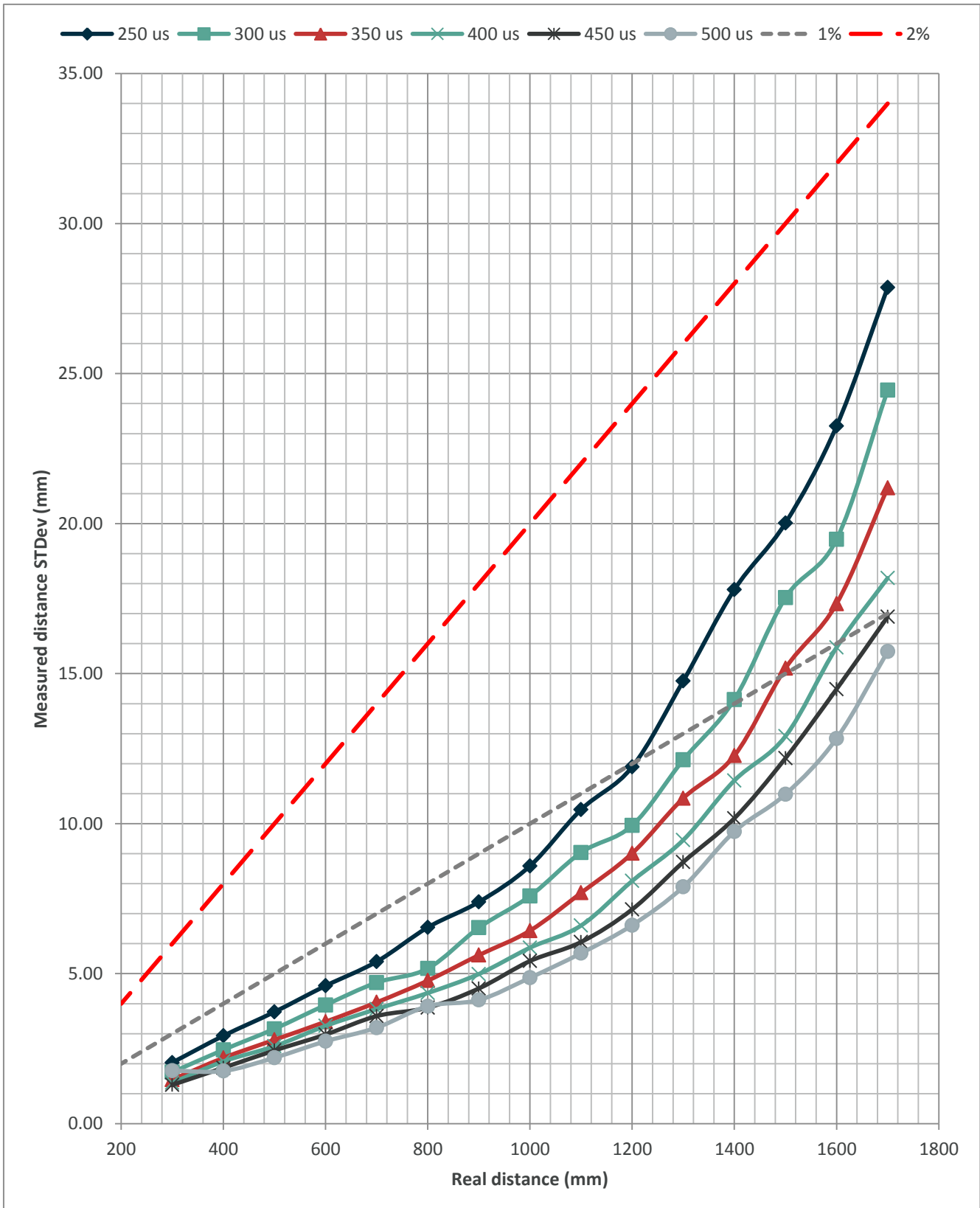
Measured distance standard deviation (STDev) of center pixel as a function of real distance,  $T_A = 25\text{ }^\circ\text{C}$ ,  $T_{int} = 250\text{ }\mu\text{s}$ ,  $F_{mod} = 20\text{ MHz}$ ,  $P_{ill} = 50\%$ , statistics over 100 frames per point, under various ambient light conditions, target reflectance is around 50 %.





### 5.3.2. Influence of the integration time on the distance noise

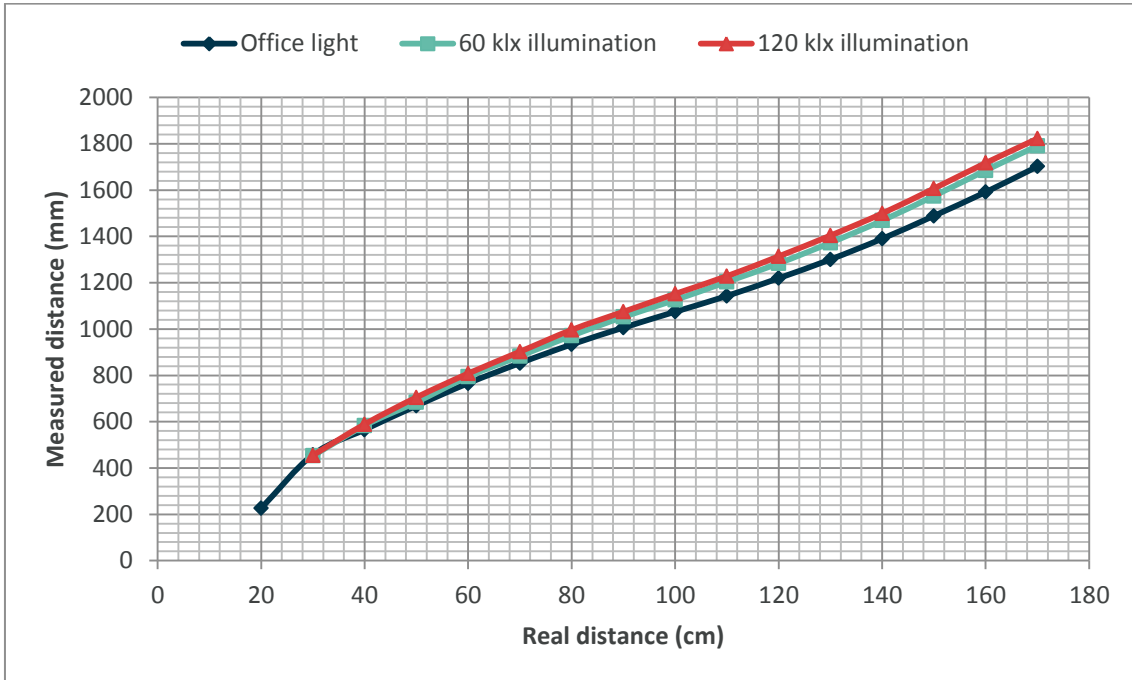
Measured distance STDev as a function of real distance,  $T_A = 25\text{ }^\circ\text{C}$ ,  $F_{mod} = 20\text{ MHz}$ ,  $P_{ill} = 50\%$ , statistics over 100 frames per point, under various ambient light conditions, target reflectance is around 50%. 60° FoV EVK was used.



### 5.3.3. Influence of the sunlight

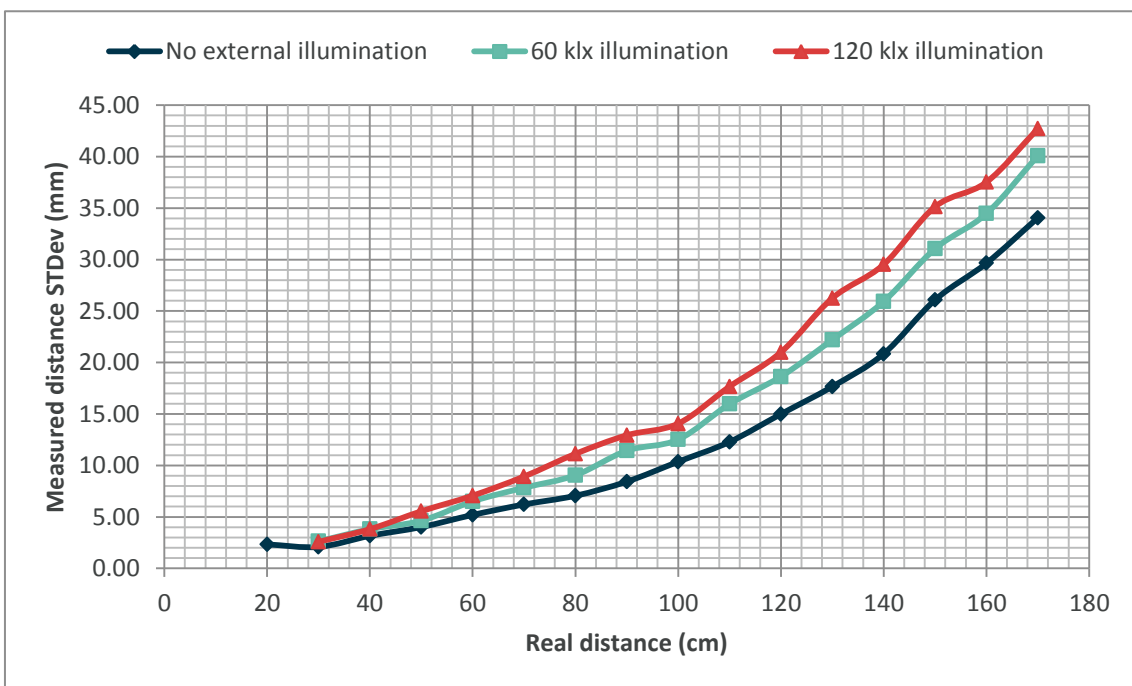
#### 5.3.3.1. Influence on linearity

Measured distance as a function of real distance,  $T_A = 25\text{ }^\circ\text{C}$ ,  $T_{int} = 250\text{ }\mu\text{s}$ ,  $F_{mod} = 20\text{ MHz}$ ,  $P_{ill} = 50\%$ , statistics over 100 frames per point, under various ambient light conditions, target reflectance is around 50%.



#### 5.3.3.2. Influence on distance noise

Measured distance STDev as a function of real distance,  $T_A = 25\text{ }^\circ\text{C}$ ,  $T_{int} = 250\text{ }\mu\text{s}$ ,  $F_{mod} = 20\text{ MHz}$ ,  $P_{ill} = 50\%$ , statistics over 100 frames per point, under various ambient light conditions, target reflectance is around 50%.

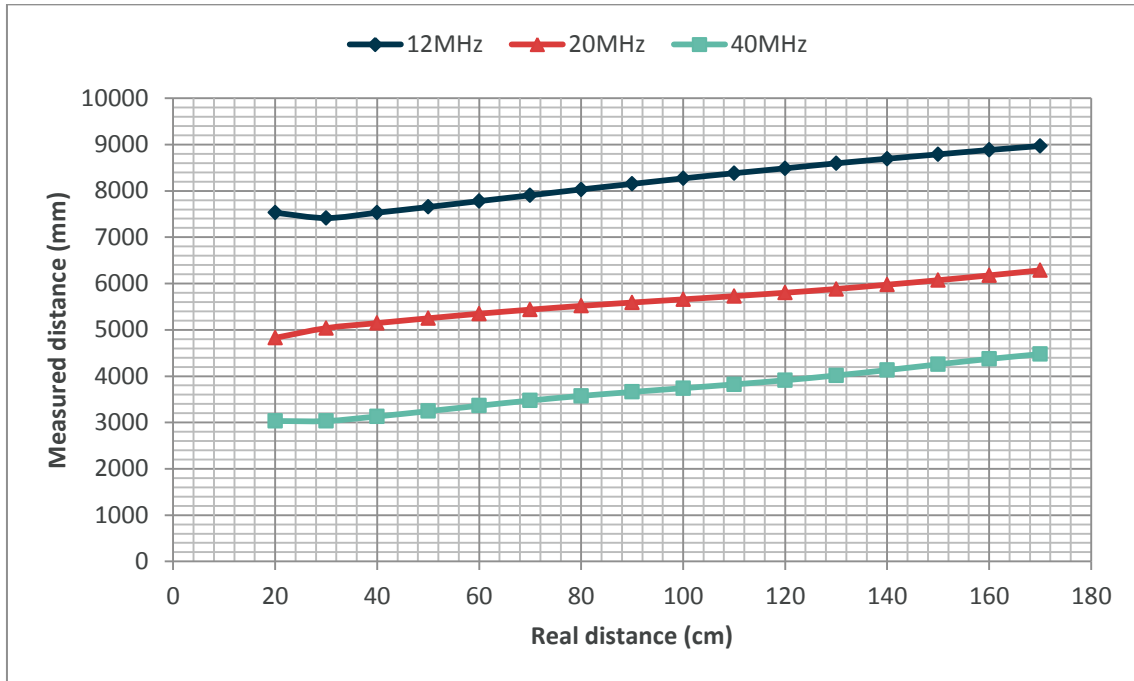


NB: Points are missing at 20cm for the 60 klx and 120 klx curves because of saturation of the sensor at close range.

### 5.3.4. Influence of the modulation frequency

#### 5.3.4.1. Influence on linearity

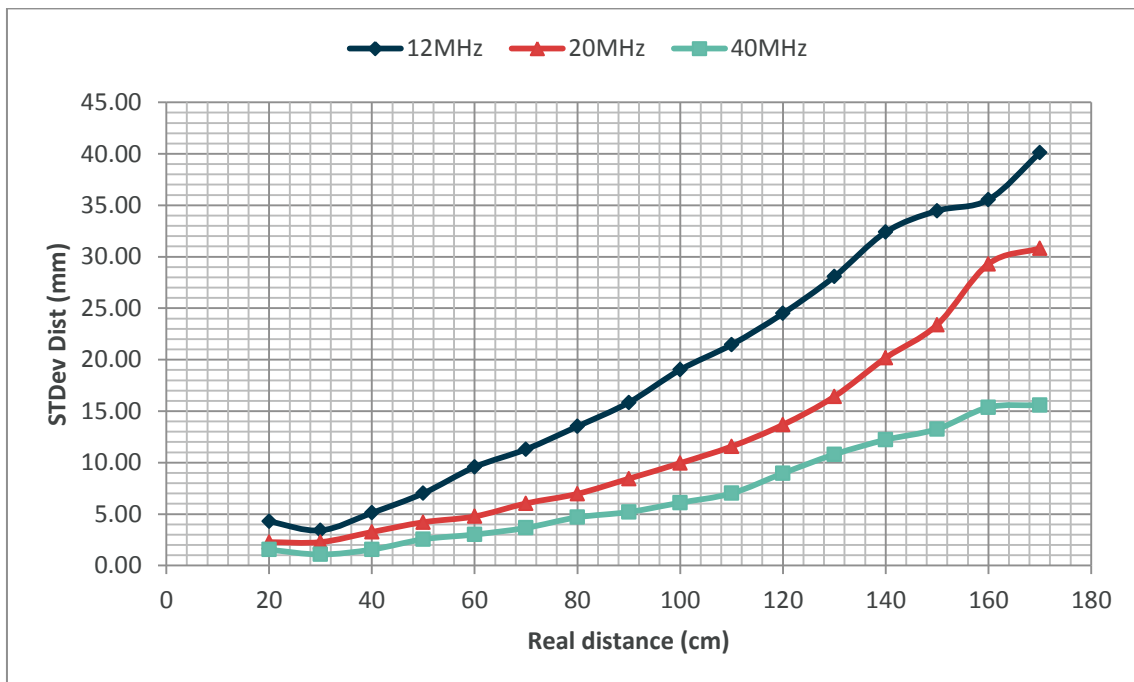
Measured distance as a function of real distance,  $T_A = 25\text{ }^\circ\text{C}$ ,  $T_{int} = 250\text{ }\mu\text{s}$ ,  $F_{mod} = 20\text{ MHz}$ ,  $P_{ill} = 50\%$ , statistics over 100 frames per point, under various ambient light conditions, target reflectance is around 50 %.



NB: The distance offset of these linearity curves depends on the modulation frequency and can be compensated using the register 0x00C1 (DistOffset00).

#### 5.3.4.2. Influence on distance noise

Measured distance STDev as a function of real distance,  $T_A = 25\text{ }^\circ\text{C}$ ,  $T_{int} = 250\text{ }\mu\text{s}$ ,  $F_{mod} = 20\text{ MHz}$ ,  $P_{ill} = 50\%$ , statistics over 100 frames per point, under various ambient light conditions, target reflectance is around 50 %.

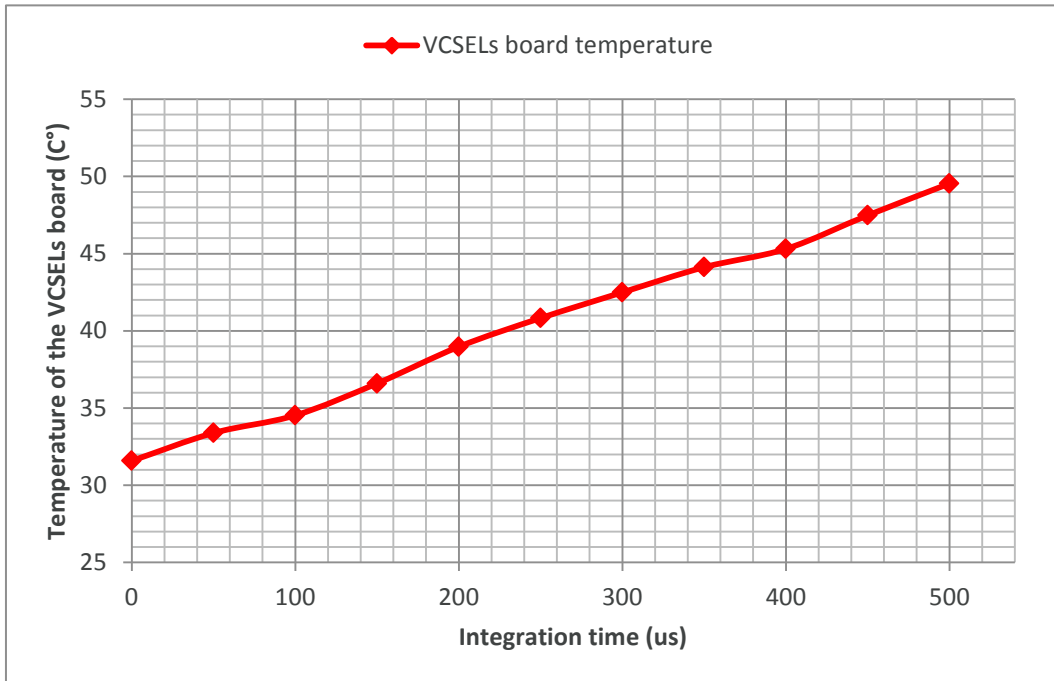


## 6. Temperature

### 6.1. Temperature of the illumination unit

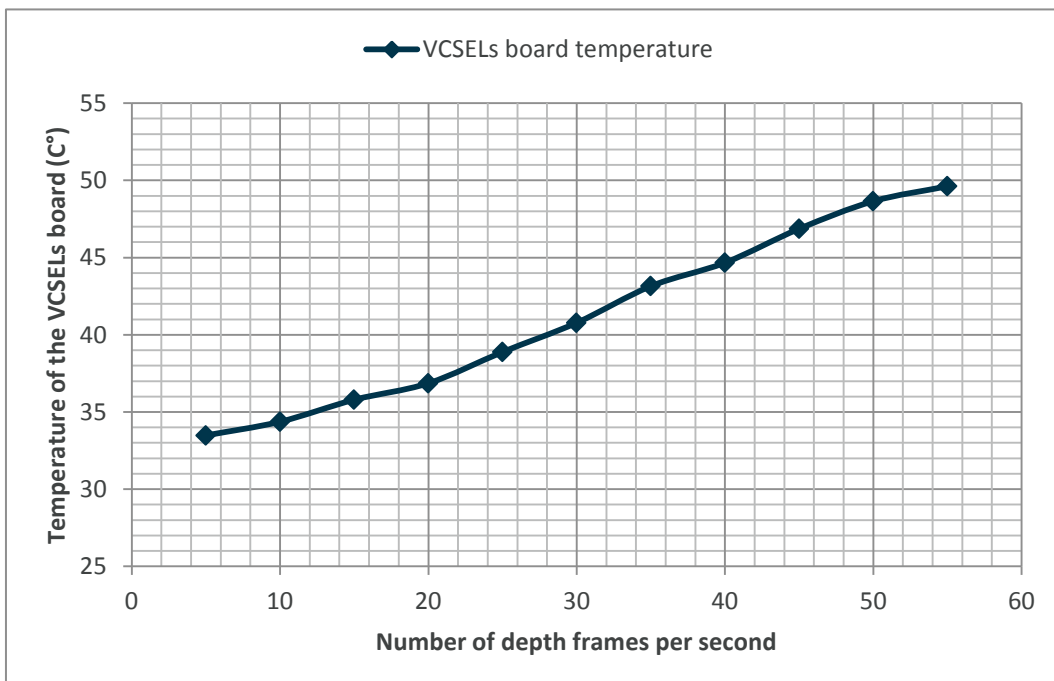
#### 6.1.1. Influence of the integration time

Temperature of the VCSELs as a function of the integration time,  $T_A = 25\text{ }^\circ\text{C}$ ,  $F_{mod} = 20\text{ MHz}$ ,  $P_{ill} = 50\%$ , 25 frames/sec.



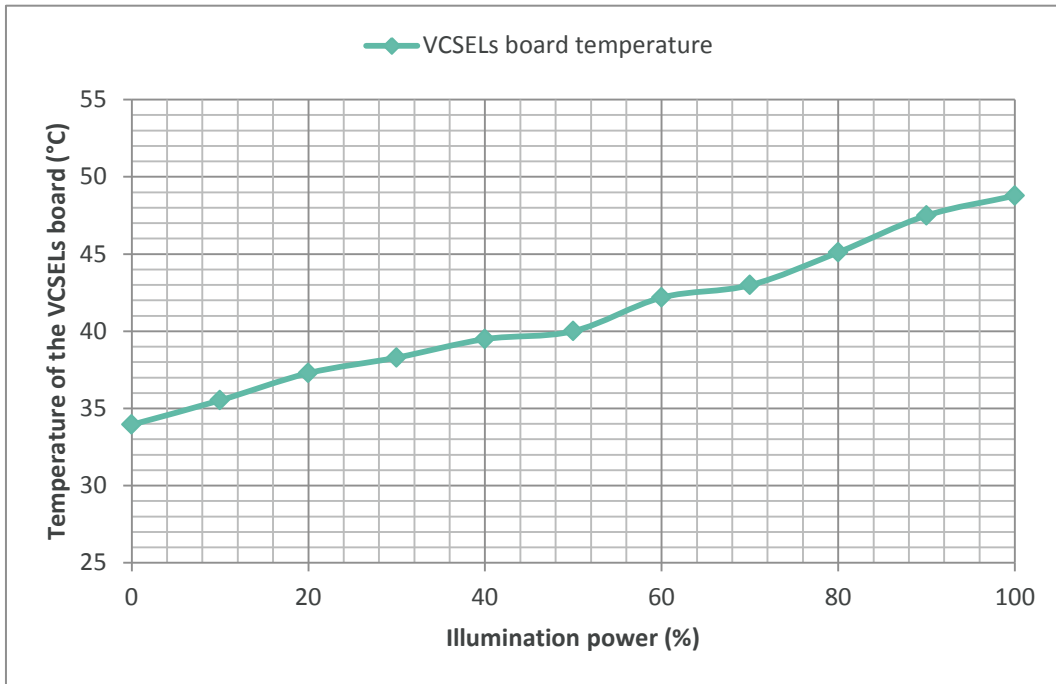
#### 6.1.2. Influence of the frame\_rate

Temperature of the VCSELs as a function of the integration time,  $T_A = 25\text{ }^\circ\text{C}$ ,  $T_{int} = 250\text{ }\mu\text{s}$ ,  $F_{mod} = 20\text{ MHz}$ ,  $P_{ill} = 50\%$ .



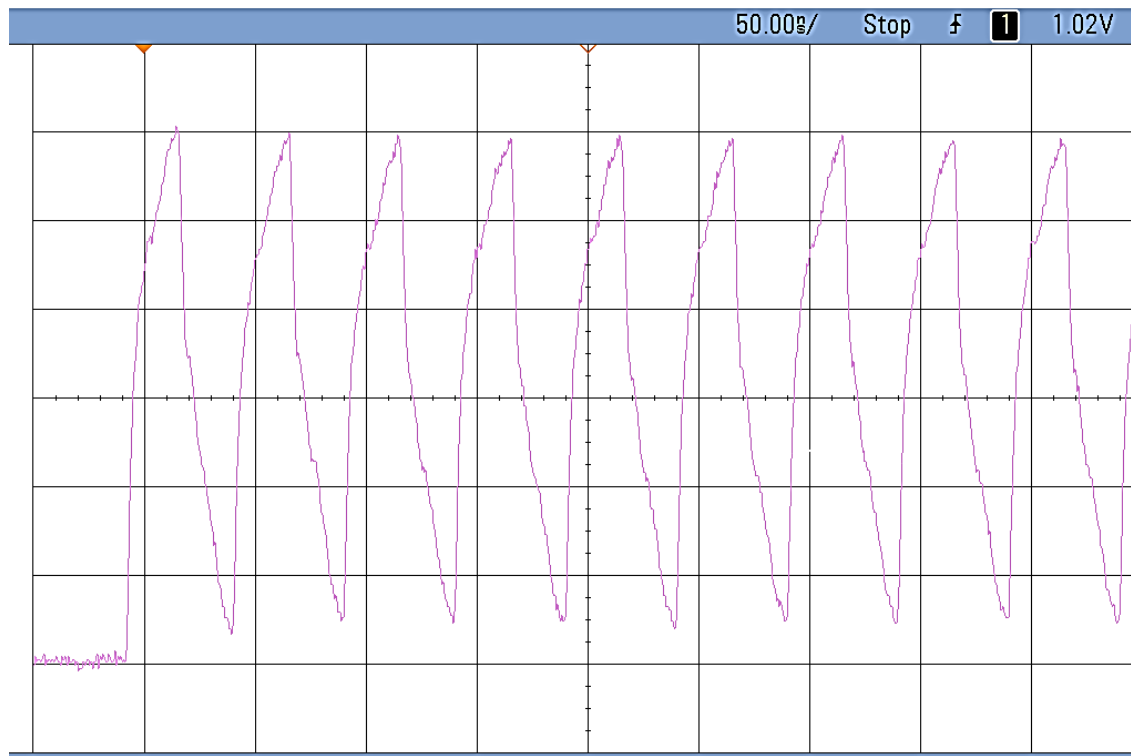
### 6.1.3. Influence of the illumination power

Temperature of the VCSELs as a function of the integration time,  $T_A = 25\text{ }^\circ\text{C}$ ,  $T_{int} = 250\text{ }\mu\text{s}$ ,  $F_{mod} = 20\text{ MHz}$ ,  $P_{ill} = 50\%$ , 25 frames/sec.

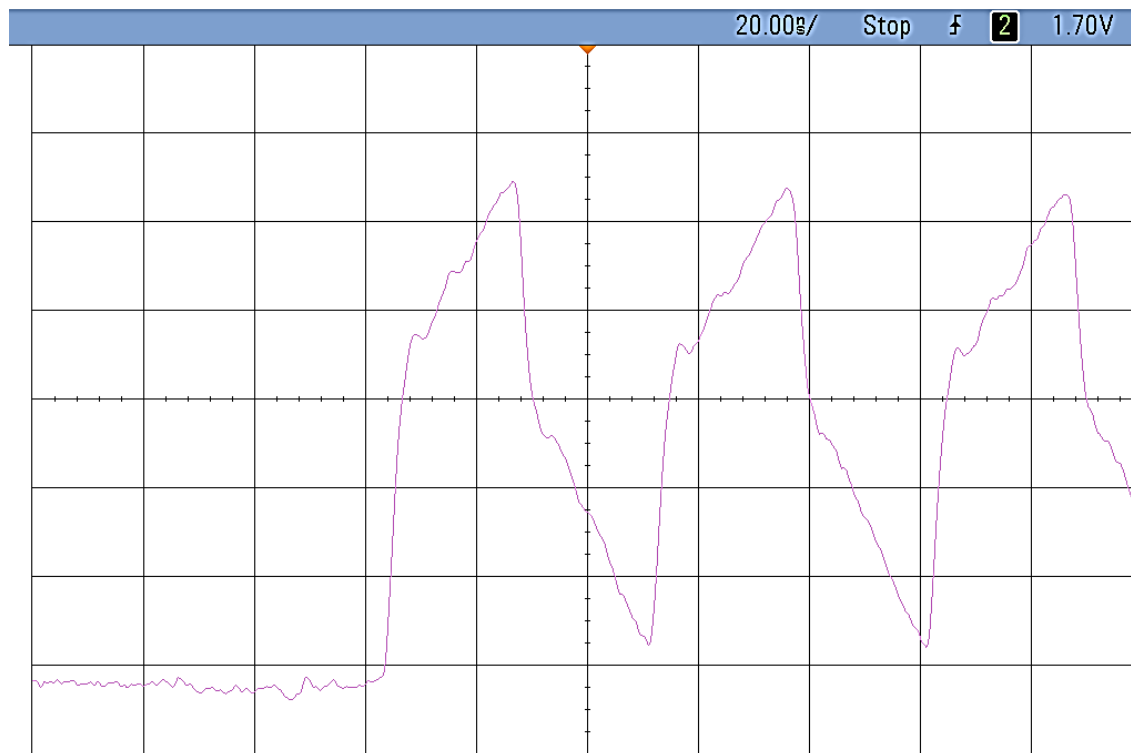


## 7. Typical light waveforms

### 7.1. Light waveform at 20MHz



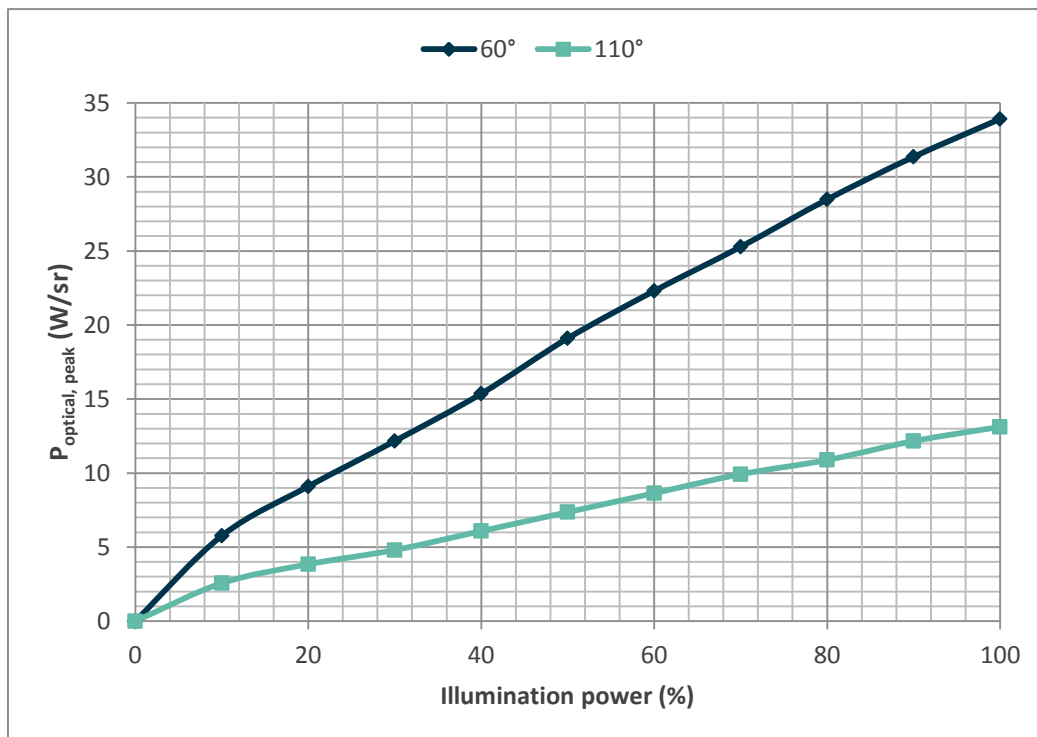
### 7.2. Light waveform at 40MHz



## 8. Optical power

### 8.1. Influence of the illumination power setting on the radiant intensity

Peak radiant intensity at the center of the image,  $r$  measured as a function of the illumination power,  $T_A = 25\text{ }^\circ\text{C}$ ,  $T_{int} = 250\text{ }\mu\text{s}$ ,  $F_{mod} = 20\text{ MHz}$ , with  $60^\circ$  EVK75123 and  $110^\circ$  EVK75123.



## 9. Warning

The use of the EVK75123 at maximum illumination power and integration time when recording frames with a high number of frames per seconds will result in important self-heating of the illumination board. This may lead the VCSELs to reach their temperature limit at around  $70^\circ\text{C}$ , in that case the evaluation kit will stop recording frames for a few seconds in order to reduce the temperature of the illumination board.

Moreover the processor at the back of the processing board is also producing a lot of heat making all the evaluation kit being hot when manipulated with bare hands, please be careful.



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